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Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test TEST Pre- and Post-Stress # E1 Electrical Test	BZX8450-C9V1-Q Part Description Nexperia DHAM SMD package Test Conditions Tamb = 25 °C JESD22-A113	Zener Duration N/A	# Lots	# Quantity	# Rejects
Assembly reliability labs Based on AEC-Q101 Test TEST Pre- and Post-Stress	Nexperia DHAM SMD package Test Conditions Tamb = 25 °C JESD22-A113	Duration	# Lots	# Quantity	# Rejects
Based on AEC-Q101 Test TEST Pre- and Post-Stress	SMD package Test Conditions Tamb = 25 °C JESD22-A113	Duration	# Lots	# Quantity	# Rejects
Based on AEC-Q101 Test TEST Pre- and Post-Stress	Test Conditions Tamb = 25 °C JESD22-A113		# Lots	# Quantity	# Rejects
TEST Pre- and Post-Stress	Tamb = 25 °C JESD22-A113		# Lots	# Quantity	# Rejects
Pre- and Post-Stress	JESD22-A113	N/A			
# E1 Electrical Test	JESD22-A113	N/A			
# E1 Electrical Test			see below	all parts	see below
# A1 Preconditioning	Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	1514	64430	0
HTRB High Temperature Reverse # B1 Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, VR = 80 % of rated reverse voltage	1000 hours	250	11400	0
SSOP # B1b Steady State Operational	MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet reverse current	1000 hours	44	1920	0
TC # A4 Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0
UHAST # A3 or Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	96 hours	311	14080	0
AC # A3 alt Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)				
H3TRB High Humidity High # A2 alt Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1]	1000 hours	311	14080	0
IOL # A5 Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	312	14120	0
RSH # C8 Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 c	269	8070	0
# C8 Resistance to Solder Heat SD # C10 Solderability	J-STD-002	10 s	19	6660	0

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

2,68E+09
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